

UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

NXP USA, INC.

Petitioner

v.

BELL SEMICONDUCTOR, LLC

Patent Owner

Case No.: IPR2024-00168

Patent No. 7,345,245

PETITIONER'S UPDATED EXHIBIT LIST

Further to 37 C.F.R. § 42.63(e), Petitioner NXP USA, Inc., hereby submits a current listing of its Updated Exhibit List to counsel for Patent Owner Bell Semiconductor, LLC. Exhibits 1021-1023 were also filed on P-TACTS on 7/17/2024 in response to the Board's email dated 7/17/2024 authorizing the submission of same and served by email to counsel of record for the Petitioner.

Exhibit No.	Description
Ex. 1001	U.S. Patent No. 7,345,245
Ex. 1002	Declaration of R. Jacob Baker, PhD, PE ("Dr. Baker")
Ex. 1003	Curriculum Vitae of Dr. Baker
Ex. 1004	File History of U.S. Patent No. 7,345,245
Ex. 1005	US Patent Pub. 2003/0183919 to Devnani et al. ("Devnani")
Ex. 1006	US Patent Pub. 2003/0003705 to Chung, et al. ("Chung")
Ex. 1007	US Patent No. 6,680,530 to Pillai et al. ("Pillai")
Ex. 1008	Mobile Intel® Celeron® Processor (0.13 μ) in Micro-FCBGA and Micro-FCPGA Packages Datasheet (April 2003) ("Celeron")
Ex. 1009	US Patent No. 6,172,305 to Tanahashi ("Tanahashi")
Ex. 1010	Thomas D. Moore and John L. Jarvis, The effects of in-plane orthotropic properties in a multi-chip ball grid array assembly, Microelectronics Reliability, Volume 42, Issue 6, June 2002, pages 943-949 ("Moore & Jarvis")

Exhibit No.	Description
Ex. 1011	D.J. Xie and Z.P. Wang, Process capability study and thermal fatigue life prediction of ceramic BGA solder joints, Finite Elements in Analysis and Design, Volume 30, Issues 1-2, July 15, 1998, pages 31-45 (“Xie and Wang”)
Ex. 1012	Memorandum from Director Vidal (dated June 21, 2022)
Ex. 1013	Scheduling Order, <i>Bell Semiconductor, LLC vs. NXP USA, INC., et al.</i> 8:22-cv-02133-HDV-ADS (C. D. California)
Ex. 1014	Reassignment Order Scheduling Order, <i>Bell Semiconductor, LLC vs. NXP USA, INC., et al.</i> 8:22-cv-02133-HDV-ADS (C. D. California)
Ex. 1015	Plaintiff Bell Semiconductor, LLC Analysis of Infringement of U.S. Patent No. 7,345,245, <i>Bell Semiconductor, LLC vs. NXP USA, INC., et al.</i> 8:22-cv-02133-HDV-ADS (C. D. California) (May 17, 2023)
Ex. 1016	Critical Review and Technology Assessments '91-'92, Reliability Analysis Center, AD-A278 419; April 21, 1994, 452 pages (“CRTA”)
Ex. 1017	2000 Packaging Handbook, Chapter 4: Performance Characteristics of IC Packages; pages 1-66, 2000 (“PCIP”)

Exhibit No.	Description
Ex. 1018	A Review of Ball Grid Arrays For Electronic Assembly, S B Dunkerton and J M Goward, Presented at ICAWT '98, The 1998 International Conference on Advances in Welding Technology - 'Joining applications in electronics and medical devices', Columbus, Ohio, USA, 30 September - 2 October 1998 ("Review of BGAs")
Ex. 1019	Order Granting Motion to Stay Pending IPR
Ex. 1020	Email dated 12 June 2024 from the Patent Trial & Appeal Board authorizing Petitioner to file a motion to supplement information pursuant to 37 C.F.R. §42.123(a).
Ex. 1021	Declaration of June Ann Munford
Ex. 1022	2 nd Declaration of R. Jacob Baker, P.E., Ph.D.
Ex. 1023	Declaration of Elizabeth Jones

Respectfully Submitted,

Dated: 7/17/2024

By: /Timothy D. Taylor/

Timothy D. Taylor (Reg. No. 76,643)
Counsel for Petitioner

CERTIFICATE OF SERVICE

I hereby certify that on 7/17/2024, Petitioner's Updated Exhibit List and Exhibits 1021-1023 were filed on P-TACTs and served via electronic service on the counsel of record for Patent Owner Bell Semiconductor, LLC; Bell-NXP-IPR@devlinlawfirm.com.

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